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NOTES:

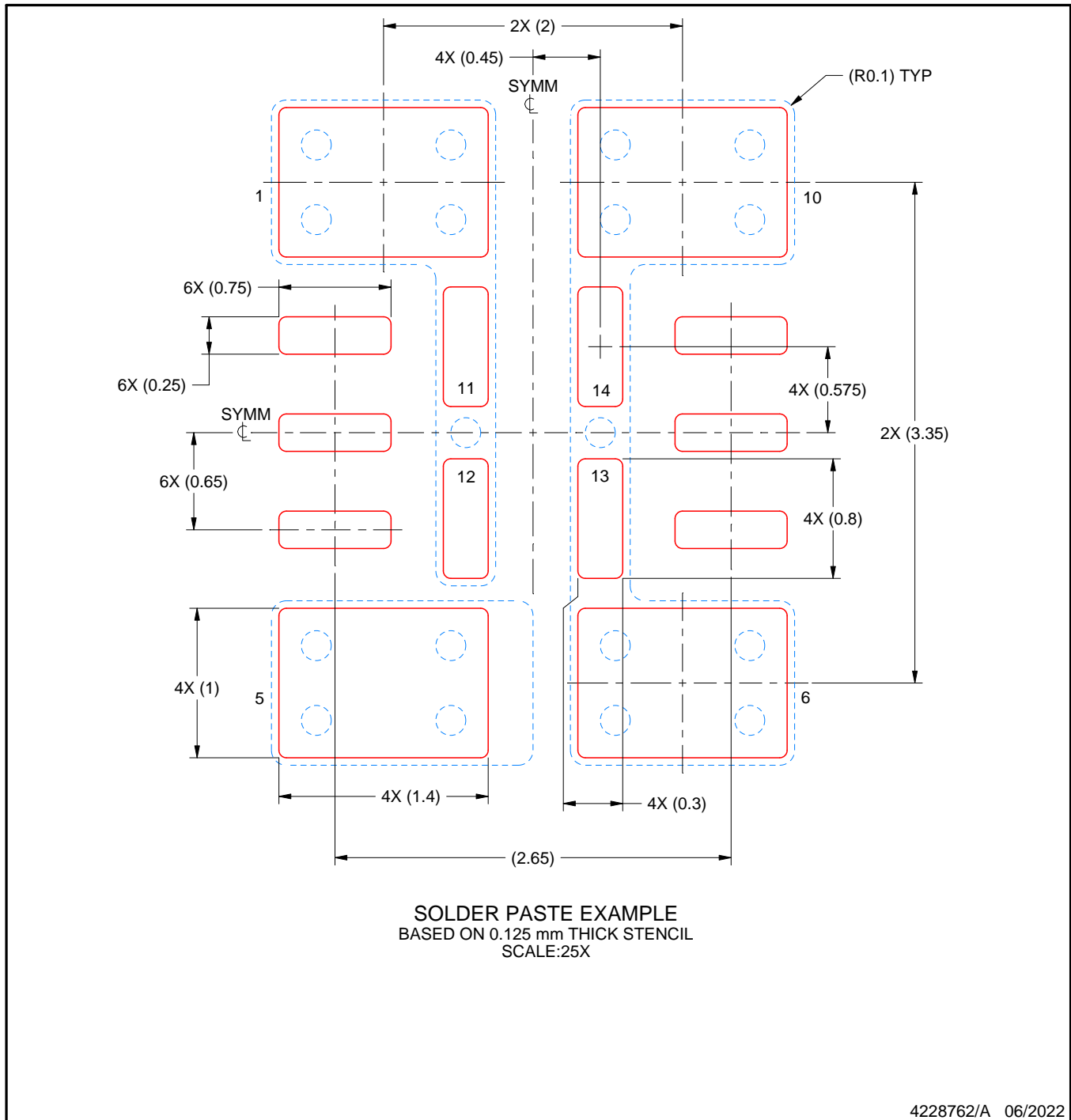
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Pick and place nozzle $\phi 1.3$ mm or smaller recommended.
4. The package thermal pads must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE STENCIL DESIGN

SIE0014A

uSIP™ - 1.6 mm max height

MICRO SYSTEM IN PACKAGE



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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